



FOR IMMEDIATE RELEASE

EV GROUP REALIZES CONTINUED GROWTH FOR FISCAL YEAR 2010 ON TOP OF AN ALREADY SUCCESSFUL PRIOR YEAR

Despite Slowed Global Economy, Company's Annual Revenue Increases More Than 20 Percent, Driven by Growing Demand Among 3D IC, CMOS Image Sensor and MEMS Markets

ST. FLORIAN, Austria, November 2, 2010 – [EV Group \(EVG\)](#), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced that the company witnessed a more than 20-percent increase in overall revenue during fiscal 2010, ended September 30. EVG attributes this growth, in large part, to continued demand for equipment used in advanced manufacturing of 3D ICs, CMOS image sensors and MEMS devices. In fact, the company reports it has grown, on average, approximately 20 percent year-over-year since 2003—successfully avoiding a drop in order intake and revenue even in 2008 and 2009 despite the global economic recession.

According to Hermann Waltl, EVG's executive sales and customer support director, the company capitalizes on its technology and market leadership by continuously building upon its extensive experience in bringing new and innovative products to market. "It's been another solid year for our company and demonstrative of our continuous investment in R&D. We firmly believe that our strong emphasis on R&D provides us with an edge in supporting our customers' increasingly sophisticated manufacturing requirements. As a result, we've witnessed continuous year-over-year growth since our inception in 1980—as well as expansion into key, high-growth markets, which has played a significant role in allowing us to successfully navigate through the ups and downs of this cyclical economy."

EVG also announced that its [EVG770 Automated NIL Stepper](#) won the prestigious fifth annual *EuroAsia Semiconductor IC Industry Award* in the category of back-end-of-line (BEOL) wafer processing. The IC Industry award winners are nominated by customers and other users of the tools. This win points to the company's excellence in service and the technology prowess of the EVG770 system, which is designed for step-and-repeat large-area UV-nanoimprint lithography (UV-NIL) processes for various applications, including 3D ICs, MEMS and CMOS image sensors.

In other news, the company recently unveiled a new technology capability that enables ultra-high-resolution patterning of features down to 12.5 nm: [Soft Molecular Scale Nanoimprint Lithography \(SMS-NIL\)](#). Based on EVG's proven UV-NIL systems, SMS-NIL provides customers with a repeatable, cost-effective process for producing ultra-high-resolution patterning on large-area surfaces. EVG also received a major order from Norway-based MEMS sensor producer Sensoror Technologies AS for its [GEMINI® fully automated wafer bonding system](#). Sensoror will use the Gemini in the production of microbolometers—thermal imaging sensors used for such applications as night vision gear for security and military applications, on-board monitors in automobiles to help detect and avoid pedestrians and animals on roads at night, and imaging systems to improve building construction.

The company also announced the latest addition to its industry-leading EVG500 Series of permanent wafer bonding systems—the new three-chamber [EVG520L3 wafer bonding system](#). The EVG520L3 addresses the need for high-vacuum, CMOS-compatible bonding processes while delivering significantly higher throughput, cost of ownership (CoO) and yields.

EVG is the platinum sponsor for this week's [MEMS Executive Congress](#), which is put on by the MEMS Industry Group (MIG). Kicking off its participation at this annual conference, EVG will be hosting its first-ever Technology Open House at its North America headquarters located at Arizona State University's Research Park.

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About EV Group

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.EVGroup.com.

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